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(54) Title: **ADHESIVE COMPOSITION**

(57) Abstract: An adhesive composition for use in the manufacture of wood-based boards, said adhesive composition containing resin and a foaming agent, and said composition being foamable. According to the invention, the adhesive composition contains 40 - 80 w-% resin, 5 - 30 w-% filler, 0 - 40 w-% solvent, and 0.1 - 10 w-% foaming agent, which has been selected from organic and/or inorganic surface-active sulfate, sulfonate, phosphate or phosphonate compounds or their derivatives or mixtures.

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